### Multilayer Ceramic Chip Capacitors

# 1 of 3 Creation Date : April 17, 2017 (GMT)

#### C1005X7R1C103K050BA



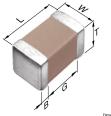






#### **TDK item description** C1005X7R1C103KT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1005 [EIA 0402]	
Status	Production (Not Recommended for New Design)	



	Size
Length(L)	1.00mm ±0.05mm
Width(W)	0.50mm ±0.05mm
Thickness(T)	0.50mm ±0.05mm
Terminal Width(B)	0.10mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.30mm to 0.50mm
Recommended Land Pattern (PB)	0.35mm to 0.45mm
Recommended Land Pattern (PC)	0.40mm to 0.60mm

Electrical Characteristics		
Capacitance	10nF ±10%	
Rated Voltage	16VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	10000ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	10000pcs

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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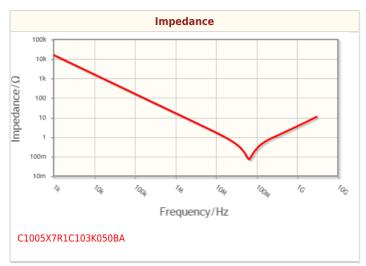


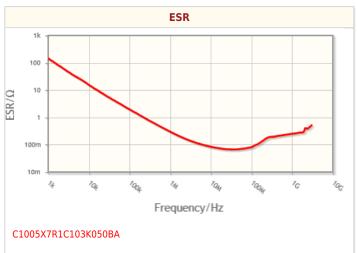


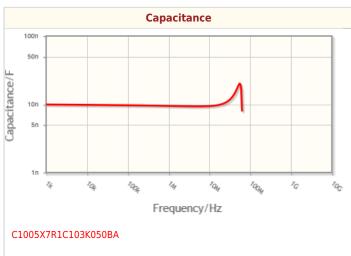


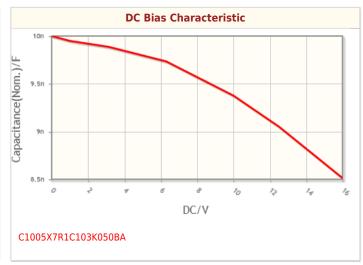


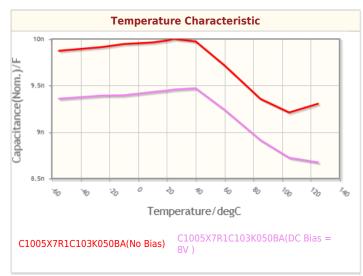
### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)













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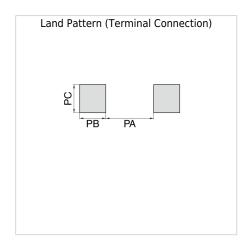






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## **Associated Images**



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